

HIGH-SPEED 3.3V 32/16K x 16 SYNCHRONOUS DUAL-PORT STATIC RAM

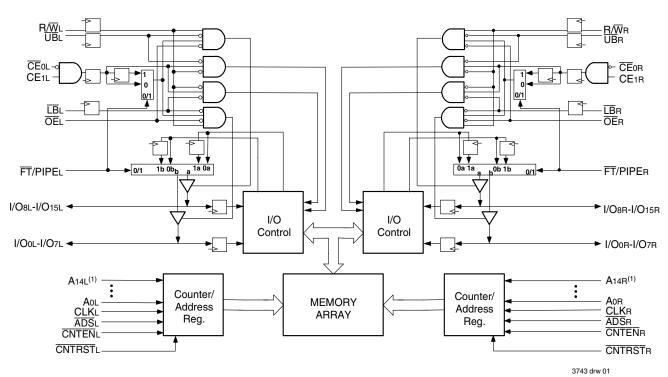
70V9279/69S/L

Features:

- True Dual-Ported memory cells which allow simultaneous access of the same memory location
- High-speed clock to data access
 - Commercial: 7.5/9ns (max.)
 - Industrial: 7.5ns (max.)
- Low-power operation
 - IDT70V9279/69L
 Active: 429mW (typ.)
 Standby: 1.32mW (typ.)
- ◆ Flow-through or Pipelined output mode on either port via the FT/PIPE pin
- Counter enable and reset features
- Dual chip enables allow for depth expansion without additional logic

- Full synchronous operation on both ports
 - 4ns setup to clock and 1ns hold on all control, data, and address inputs
 - Data input, address, and control registers
 - Fast 6.5ns clock to data out in the Pipelined output mode
 - Self-timed write allows fast cycle time
 - 10ns cycle time, 100MHz operation in Pipelined output mode
- Separate upper-byte and lower-byte controls for multiplexed bus and bus matching compatibility
- LVTTL- compatible, single 3.3V (±0.3V) power supply
- Industrial temperature range (-40°C to +85°C) is available for selected speeds
- Available in a 128-pin Thin Quad Flatpack (TQFP) package
- Green parts available, see ordering information

Functional Block Diagram



NOTE:

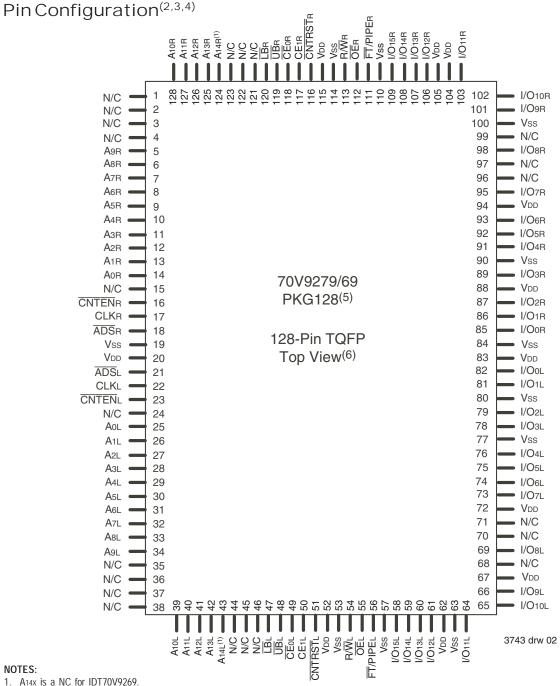
1. A₁₄x is a NC for IDT70V9269.

AUGUST 2019

Description:

The IDT70V9279/69 is a high-speed 32/16K x 16 bit synchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times.

With an input data register, the IDT70V9279/69 has been optimized for applications having unidirectional or bidirectional data flow in bursts. An automatic power down feature, controlled by \overline{CE}_0 and CE₁, permits the on-chip circuitry of each port to enter a very low standby power mode. Fabricated using CMOS high-performance technology, these devices typically operate on only 429mW of power.



- 1. A14x is a NC for IDT70V9269.
- 2. All V_{DD} pins must be connected to power supply.
- 3. All Vss pins must be connected to ground.
- Package body is approximately 14mm x 20mm x 1.4mm.
- This package code is used to reference the package diagram.
- This text does not indicate orientation of the actual part-marking.



Pin Names

Left Port	Right Port	Names
CEOL, CE1L	CEOR, CE1R	Chip Enables ⁽³⁾
R/WL	R/WR	Read/Write Enable
ŌĒL	OE R	Output Enable
A0L - A14L ⁽¹⁾	A0R - A14R ⁽¹⁾	Address
I/O0L - I/O15L	I/O0R - I/O15R	Data Input/Output
CLKL	CLKR	Clock
Ū <u>B</u> L	Ū B R	Upper Byte Select ⁽²⁾
<u>TB</u> ∟	<u>T</u> BR	Lower Byte Select ⁽²⁾
ĀDSL	ADS R	Address Strobe Enable
CNTENL	<u>CNTEN</u> R	Counter Enable
CNTRSTL	<u>CNTRST</u> R	Counter Reset
FT/PIPEL	FT/PIPER	Flow-Through / Pipeline
,	VDD	Power (3.3V)
	Vss	Ground (0V)

1. Address A_{14x} is a NC for IDT70V9269.

NOTES:

- 2. \overline{LB} and \overline{UB} are single buffered regardless of state of $\overline{FT}/PIPE$.
- CE₀ and CE₁ are single buffered when FT/PIPE = V_{IL},
 CE₀ and CE₁ are double buffered when FT/PIPE = V_{IH},
 i.e. the signals take two cycles to deselect.

3743 tbl 01

Truth Table I—Read/Write and Enable Control^(1,2,3)

ŌĒ	CLK	<u>C</u> E₀ ⁽⁵⁾	CE1 ⁽⁵⁾	UB ⁽⁴⁾	LB ⁽⁴⁾	R/W	Upper Byte I/O ₈₋₁₅	Lower Byte I/O ₀₋₇	MODE
Χ	1	Н	Х	Χ	Χ	Χ	High-Z	High-Z	Deselected-Power Down
Х	1	Χ	L	Χ	Χ	Χ	High-Z	High-Z	Deselected-Power Down
Х	1	L	Н	Н	Н	Х	High-Z	High-Z	Both Bytes Deselected
Х	1	L	Н	L	Н	L	Din	High-Z	Write to Upper Byte Only
Χ	1	L	Н	Н	L	L	High-Z	DATAIN	Write to Lower Byte Only
Χ	1	L	Н	L	L	L	DATAIN	DATAIN	Write to Both Bytes
L	1	L	Н	L	Н	Н	DATAout	High-Z	Read Upper Byte Only
L	1	L	Н	Н	L	Н	High-Z	DATAout	Read Lower Byte Only
L	1	L	Н	L	L	Н	DATAout	DATAout	Read Both Bytes
Н	1	L	Н	L	L	Χ	High-Z	High-Z	Outputs Disabled

NOTES: 3743 tbl 02

- 1. "H" = VIH, "L" = VIL, "X" = Don't Care.
- 2. ADS, CNTEN, CNTRST = X.
- 3. OE is an asynchronous input signal.
- 4 \overline{LB} and \overline{UB} are single buffered regardless of state of $\overline{FT}/\overline{PIPE}$.
- 5. $\overline{\text{CE}}$ o and CE1 are single buffered when $\overline{\text{FT}}/\text{PIPE} = \text{V}_{\text{IL}}$. $\overline{\text{CE}}$ o and CE1 are double buffered when $\overline{\text{FT}}/\text{PIPE} = \text{V}_{\text{IH}}$, i.e. the signals take two cycles to deselect.

Truth Table II—Address Counter Control (1,2,3)

11011		/ \									
External Address	Previous Internal Address	Internal Address Used	CLK	ĀDS	CNTEN	CNTRST	I/O ⁽³⁾	MODE			
An	Х	An	↑	L ⁽⁴⁾	Χ	Н	Dvo (n)	External Address Used			
Х	An	An + 1	1	Н	L ⁽⁵⁾	Н	Dvo(n+1)	Counter Enabled—Internal Address generation			
Х	An + 1	An + 1	1	Н	Н	Н	Dvo(n+1)	External Address Blocked—Counter disabled (An + 1 reused)			
Х	Х	A 0	1	Χ	Х	L ⁽⁴⁾	Dvo(0)	Counter Reset to Address 0			

NOTES: 3743 tbl 03

- 1. "H" = VIH, "L" = VIL, "X" = Don't Care.
- 2. \overline{CE}_0 , \overline{LB} , \overline{UB} , and \overline{OE} = VIL; CE1 and R/ \overline{W} = VIH.
- 3. Outputs configured in Flow-Through Output mode; if outputs are in Pipelined mode the data out will be delayed by one cycle.
- 4. ADS and CNTRST are independent of all other signals including CEo, CE1, UB and LB.
- 5. The address counter advances if CNTEN = VIL on the rising edge of CLK, regardless of all other signals including CEo, CE₁, UB and UB.

Recommended Operating Temperature and Supply Voltage^(1,2)

Grade	Ambient Temperature	GND	V DD
Commercial	0°C to +70°C	0V	3.3V <u>+</u> 0.3V
Industrial	-40°C to +85°C	0V	3.3V <u>+</u> 0.3V

NOTES: 3743 tbl 04

- Industrial temperature: for specific speeds, packages and powers contact your sales office.
- 2. This is the parameter Ta. This is the "instant on" case temperature.

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
VDD	Supply Voltage	3.0	3.3	3.6	V
Vss	Ground	0	0	0	V
VIH	Input High Voltage	2.2	_	V _{DD} +0.3V ⁽²⁾	V
VIL	Input Low Voltage	-0.3 ⁽¹⁾	_	0.8	V

3743 tbl 05

3743 tbl 07

NOTES:

- 1. $VIL \ge -1.5V$ for pulse width less than 10 ns.
- 2. VTERM must not exceed VDD + 0.3V.

Absolute Maximum Ratings⁽¹⁾

Symbol	Rating	Commercial & Industrial	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	٧
TBIAS ⁽³⁾	Temperature Under Bias	-55 to +125	°C
Тѕтс	StorageTemperature	-65 to +150	°C
NuT	Junction Temperature	+150	°C
Іоит	DC Output Current	50	mA

3743 tbl 06

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may
 cause permanent damage to the device. This is a stress rating only and functional
 operation of the device at these or any other conditions above those indicated
 in the operational sections of this specification is not implied. Exposure to absolute
 maximum rating conditions for extended periods may affect reliability.
- 2. VTERM must not exceed VDD + 0.3V for more than 25% of the cycle time or 10ns maximum, and is limited to \leq 20mA for the period of VTERM \geq VDD + 0.3V.
- 3. Ambient Temperature Under DC Bias. No AC Conditions. Chip Deselected.

Capacitance⁽¹⁾

 $(TA = +25^{\circ}C, f = 1.0MHz)$

Symbol	Parameter	Conditions	Мах.	Unit
CIN	Input Capacitance	VIN = 0V	9	pF
Cout ⁽²⁾	Output Capacitance	Vout = 0V	10	pF

- These parameters are determined by device characterization, but are not production tested.
- 2. Cout also references Ci/o.

DC Electrical Characteristics Over the Operating

Temperature and Supply Voltage Range (VDD = 3.3V ± 0.3V)

			70V92	79/69S	70V92		
Symbol	Parameter	Test Conditions	Min.	Max.	Min.	Max.	Unit
Iu	Input Leakage Current ⁽¹⁾	$V_{DD} = 3.6V$, $V_{IN} = 0V$ to V_{DD}	_	10	-	5	μΑ
ILO	Output Leakage Current	$\overline{\text{CEO}}$ = Vih or CE1 = Vil., Vout = 0V to Vdd	_	10	_	5	μΑ
Vol	Output Low Voltage	IOL = +4mA	_	0.4	_	0.4	V
Vон	Output High Voltage	Iон = -4mA	2.4	_	2.4	_	V

NOTE:

1. At VDD ≤ 2.0V input leakages are undefined.

3743 tbl 08

3743 tbl 09a

DC Electrical Characteristics Over the Operating Temperature Supply Voltage Range^(3,6) (VDD = 3.3V ± 0.3V)

	·	ppry vortage R		-		79/69X6 I Only	Co	79/69X7 m'l Ind		79/69X9 Only	
Symbol	Parameter	Test Condition	Versio	n	Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	Typ. ⁽⁴⁾	Max.	Unit
IDD	Dynamic Operating Current (Both	CEL and CER= VIL, Outputs Disabled,	COM'L	S L	220 220	395 350	200 200	335 290	180 180	260 225	mA
	Ports Active)	$f = fMAX^{(1)}$	IND	S L			200 200	370 335			
ISB1	Standby Current (Both Ports - TTL	$\overline{CEL} = \overline{CER} = VIH$ $f = fMAX^{(1)}$	COM'L	S L	70 70	145 130	60 60	115 100	50 50	75 65	mA
	Level Inputs)		IND	S L		_	60 60	130 115	_		
ISB2	Standby Current (One Port - TTL	\overline{CE} "A" = VIL and \overline{CE} "B" = VIH ⁽⁵⁾	COM'L	S L	150 150	280 250	130 130	240 210	110 110	170 150	mA
	Level Inputs)	Active Port Outputs Disabled, f=fMAX ⁽¹⁾	IND	S L			130 130	265 240			
ISB3	Full Standby Current (Both Ports - CMOS	Both Ports $\overline{CE}L$ and $\overline{CE}R \ge VDD - 0.2V$,	COM'L	S L	1.0 0.4	5 3	1.0 0.4	5 3	1.0 0.4	5 3	mA
	Level Inputs)	$\begin{array}{l} \text{VIN} \geq \text{VDD} - 0.2 \text{V or} \\ \text{VIN} \leq 0.2 \text{V, f} = 0^{(2)} \end{array}$	IND	S L			1.0 0.4	20 15	_		
ISB4	Full Standby Current (One Port - CMOS	nt (One \overline{CE} "B" $\geq V_{DD} - 0.2V^{(5)}$	COM'L	S L	140 140	270 240	120 120	230 200	100 100	160 140	mA
	Level Inputs)	$ \begin{array}{l} \text{VIN} \geq \text{Vdd} - 0.2 \text{V or} \\ \text{VIN} \leq 0.2 \text{V, Active Port,} \\ \text{Outputs Disabled, } f = \text{fmax}^{(1)} \\ \end{array} $	IND	S L			120 120	255 230			

- 1. At f = fmax, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of Vss to 3V.
- 2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.
- 3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- 4. VDD = 3.3V, TA = 25°C for Typ, and are not production tested. IDD DC(f=0) = 90mA (Typ).

 5. \overline{\text{CEx}} = \text{VIL means } \overline{\text{CEx}} = \text{VIL and } \text{CE1x} = \text{VIH}
- - $\overline{CE}x = V_{IH} \text{ means } \overline{CE}_{0X} = V_{IH} \text{ or } CE_{1X} = V_{IL}$
 - $\overline{\text{CE}}\text{x} \leq 0.2 \text{V}$ means $\overline{\text{CE}}\text{ox} \leq 0.2 \text{V}$ and $\text{CE}\text{1x} \geq \text{V}\text{dd} 0.2 \text{V}$
 - $\overline{\text{CE}}$ x \geq Vdd 0.2V means $\overline{\text{CE}}$ 0x \geq Vdd 0.2V or CE1x \leq 0.2V
 - 'X' represents "L" for left port or "R" for right port.
- 6. 'X' in part numbers indicate power rating (S or L).

3743 tbl 09b



70V9279/69S/L High-Speed 32/16K x 16 Dual-Port Synchronous Static RAM

DC Electrical Characteristics Over the Operating Temperature Supply Voltage Range^(3,6) (VDD = $3.3V \pm 0.3V$)(Cont'd)

70V9279/69X12 70V9279/69X15 Com'l Only Com'l Only Typ.⁽⁴⁾ Typ.⁽⁴⁾ Parameter **Test Condition** Version Max. Unit Symbol Max CEI and CER= VII. COM'L Dynamic 150 240 130 mA Operating Current (Both Ĺ 150 205 130 185 Outputs Disabled. $f = fMAX^{(1)}$ Ports Active) IND S $\overline{CE}L = \overline{CE}R = VIH$ COM'L S 40 65 30 55 ISB1 Standby mΑ Current (Both L 40 50 30 35 Ports - TTL $f = fMAX^{(1)}$ IND S Level Inputs) ISB2 Standby \overline{CE} "A" = VIL and COM'L S 100 160 90 mΑ 150 Current (One Ĺ \overline{CE} "B" = VIH(5) 100 140 90 130 Port - TTL Active Port Outputs Disabled, IND S Level Inputs) f=fmax⁽¹⁾ Ĺ Both Ports CEL and ISB3 Full Standby COM'L S 1.0 5 1.0 5 mΑ Current (Both $\overline{CER} \ge VDD - 0.2V$ 0.4 3 0.4 3 $VIN \ge VDD - 0.2V \text{ or } VIN \le 0.2V, f = 0^{(2)}$ Ports - CMOS IND S Level Inputs) L Full Standby ISB4 \overline{CE} "A" \leq 0.2V and COM'L S 150 mΑ 90 80 140 \overline{CE} "B" $\geq V_{DD} - 0.2V^{(5)}$ Current (One L 90 130 80 120 Port - CMOS $VIN \ge \overline{V}DD - 0.2V$ or Level Inputs) $VIN \leq 0.2V$, Active Port, IND S Outputs Disabled, f = fMAX⁽¹⁾

- 1. At f = fmax, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of Vss to 3V.
- 2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.
- 3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- 4. $V_{DD} = 3.3V$, $T_{A} = 25$ °C for Typ, and are not production tested. $I_{DD} DC(f=0) = 90 \text{mA}$ (Typ).
- 5. $\overline{CE}x = VIL \text{ means } \overline{CE}_{0x} = VIL \text{ and } CE_{1x} = VIH$
 - $\overline{CE}x = VIH \text{ means } \overline{CE}0x = VIH \text{ or } CE1x = VIL$

 - 'X' represents "L" for left port or "R" for right port.
- 6. 'X' in part numbers indicate power rating (S or L).



AC Test Conditions

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	Figures 1, 2, and 3

7343 tbl 10

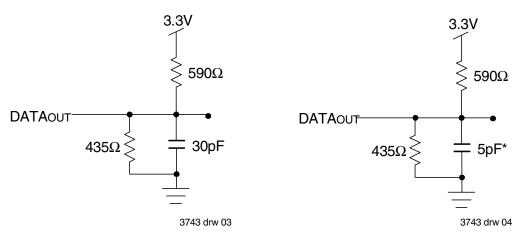


Figure 1. AC Output Test load.

Figure 2. Output Test Load (For tcklz, tckHz, tolz, and toHz). *Including scope and jig.

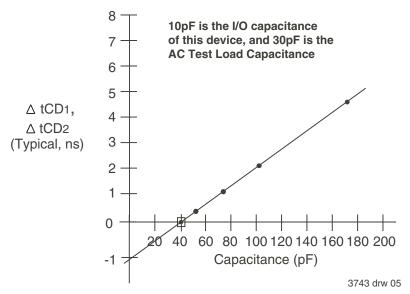


Figure 3. Typical Output Derating (Lumped Capacitive Load).



AC Electrical Characteristics Over the Operating Temperature Range (Pead and Write Cycle Timing) (3,4) (ypp = 3,2) y = 0,2) = 70°C to +70°C)

	and Write Cycle Timing) ^(3,4) (70V92	79/69X6 I Only	70V92	79/69X7 om'l Ind	70V9279/69X9 Com'l Only		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Unit
tcyc1	Clock Cycle Time (Flow-Through) ⁽²⁾	19	_	22	_	25	_	ns
tcyc2	Clock Cycle Time (Pipelined) ⁽²⁾	10	_	12	_	15		ns
tcH1	Clock High Time (Flow-Through) ⁽²⁾	6.5	_	7.5	_	12		ns
tcl1	Clock Low Time (Flow-Through) ⁽²⁾	6.5	_	7.5	_	12		ns
tCH2	Clock High Time (Pipelined) ⁽²⁾	4	_	5	_	6		ns
tCL2	Clock Low Time (Pipelined) ⁽²⁾	4	_	5	_	6		ns
tr	Clock Rise Time	_	3		3	_	3	ns
tF	Clock Fall Time	_	3		3	_	3	ns
tsa	Address Setup Time	3.5	_	4	_	4	_	ns
tha	Address Hold Time	0	_	0	_	1	_	ns
tsc	Chip Enable Setup Time	3.5	_	4	_	4	_	ns
thc	Chip Enable Hold Time	0	_	0	_	1	_	ns
tsw	R/W Setup Time	3.5	_	4	_	4	_	ns
tHW	R/W Hold Time	0	_	0	_	1	_	ns
tsd	Input Data Setup Time	3.5	_	4	_	4	_	ns
thd	Input Data Hold Time	0	_	0	_	1	_	ns
tsad	ADS Setup Time	3.5	_	4	_	4	_	ns
thad	ADS Hold Time	0	_	0	_	1	_	ns
tscn	CNTEN Setup Time	3.5	_	4	_	4	_	ns
thcn	CNTEN Hold Time	0	_	0	_	1	_	ns
tsrst	CNTRST Setup Time	3.5	_	4	_	4	_	ns
thrst	CNTRST Hold Time	0	_	0	_	1		ns
toe	Output Enable to Data Valid	_	6.5		7.5	_	9	ns
tolz	Output Enable to Output Low-Z ⁽¹⁾	2	_	2	_	2		ns
tонz	Output Enable to Output High-Z ⁽¹⁾	1	7	1	7	1	7	ns
tcD1	Clock to Data Valid (Flow-Through) ⁽²⁾	_	15		18	_	20	ns
tCD2	Clock to Data Valid (Pipelined) ⁽²⁾	_	6.5		7.5	_	9	ns
toc	Data Output Hold After Clock High	2	_	2	_	2	_	ns
tскнz	Clock High to Output High-Z ⁽¹⁾	2	9	2	9	2	9	ns
tcklz	Clock High to Output Low-Z ⁽¹⁾	2	_	2	_	2	_	ns
Port-to-Port [Delay	•	•					
tcwdd	Write Port Clock High to Read Data Delay	_	24	_	28	_	35	ns
tccs	Clock-to-Clock Setup Time	_	9	_	10	_	15	ns
						1		

^{1.} Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed by device characterization, but is not production tested.

^{2.} The Pipelined output parameters (tcyc2, tcp2) apply to either or both left and right ports when FT/PIPE = VIH. Flow-through parameters (tcyc1, tcp1) apply when $\overline{FT}/PIPE = V_{IL}$ for that port.

^{3.} All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE) and FT/PIPE. FT/PIPE should be treated as a DC signal, i.e. steady state during operation.

^{4. &#}x27;X' in part number indicates power rating (S or L).



AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing) $^{(3,4)}$ (VDD = 3.3V ± 0.3V, TA = 0°C to +70°C)(Cont'd)

			9/69X12 I Only	70V927 Com'	/9/69X15 I Only	
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
tcyc1	Clock Cycle Time (Flow-Through) ⁽²⁾	30	_	35	_	ns
tcyc2	Clock Cycle Time (Pipelined) ⁽²⁾	20	_	25	_	ns
tcH1	Clock High Time (Flow-Through) ⁽²⁾	12	_	12	_	ns
tCL1	Clock Low Time (Flow-Through) ⁽²⁾	12	_	12	_	ns
tCH2	Clock High Time (Pipelined) ⁽²⁾	8	_	10	_	ns
tCL2	Clock Low Time (Pipelined) ⁽²⁾	8	_	10	_	ns
tr	Clock Rise Time		3	_	3	ns
tF	Clock Fall Time	_	3	_	3	ns
tsa	Address Setup Time	4	_	4	_	ns
tha	Address Hold Time	1	_	1	_	ns
tsc	Chip Enable Setup Time	4	_	4	_	ns
thc	Chip Enable Hold Time	1	_	1	_	ns
tsw	R/W Setup Time	4	_	4	_	ns
thw	R/W Hold Time	1	_	1	_	ns
tsd	Input Data Setup Time	4	_	4	_	ns
thD	Input Data Hold Time	1	_	1	_	ns
tsad	ADS Setup Time	4	_	4	_	ns
thad	ADS Hold Time	1		1		ns
tscn	CNTEN Setup Time	4		4		ns
thcn	CNTEN Hold Time	1	_	1	_	ns
tsrst	CNTRST Setup Time	4		4		ns
thrst	CNTRST Hold Time	1	_	1	_	ns
toe	Output Enable to Data Valid		12	_	15	ns
tolz	Output Enable to Output Low-Z ⁽¹⁾	2	_	2	_	ns
toнz	Output Enable to Output High-Z ⁽¹⁾	1	7	1	7	ns
tcD1	Clock to Data Valid (Flow-Through) ⁽²⁾		25	_	30	ns
tCD2	Clock to Data Valid (Pipelined) ⁽²⁾		12	_	15	ns
toc	Data Output Hold After Clock High	2	_	2	_	ns
tckhz	Clock High to Output High-Z ⁽¹⁾	2	9	2	9	ns
tcklz	Clock High to Output Low-Z ⁽¹⁾	2	_	2	_	ns
Port-to-Port [Delay					
tcwdd	Write Port Clock High to Read Data Delay		40	_	50	ns
tccs	Clock-to-Clock Setup Time		15	_	20	ns

^{1.} Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed by device characterization, but is not production tested.

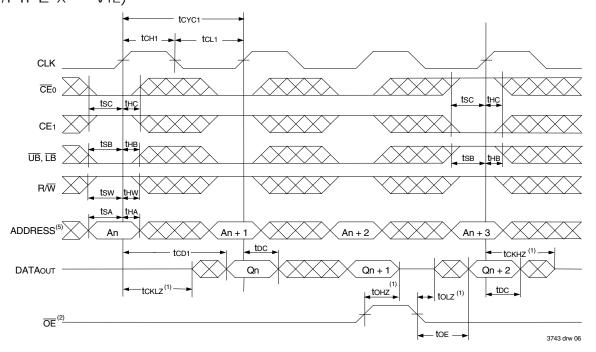
^{2.} The Pipelined output parameters (tcvc2, tcb2) apply to either or both left and right ports when FT/PIPE = VIH. Flow-through parameters (tcvc1, tcb1) apply when FT/PIPE = VIL for that port.

^{3.} All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE) and FT/PIPE. FT/PIPE should be treated as a DC signal, i.e. steady state during operation.

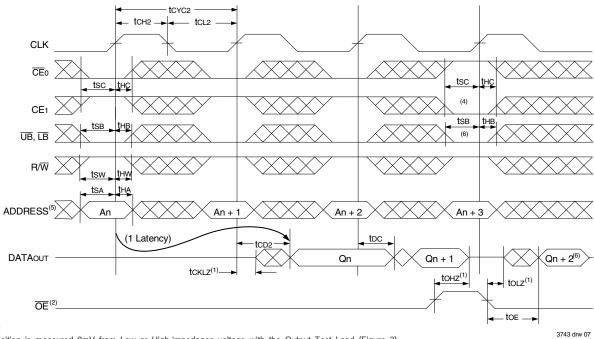
^{4. &#}x27;X' in part number indicates power rating (S or L).



Timing Waveform of Read Cycle for Flow-through Output $(\mathbf{FT}/PIPE"x" = VIL)^{(3,7)}$



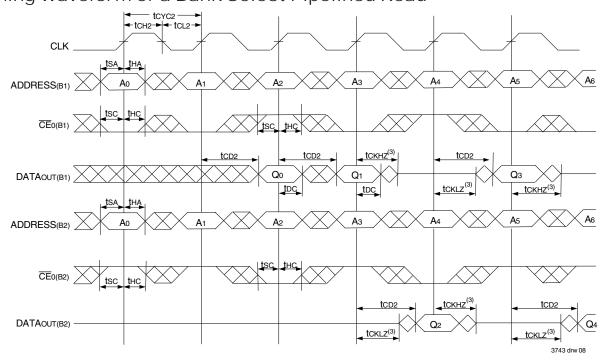
Timing Waveform of Read Cycle for Pipelined Output $(\mathbf{FT}/PIPE"x" = VIH)^{(3,7)}$



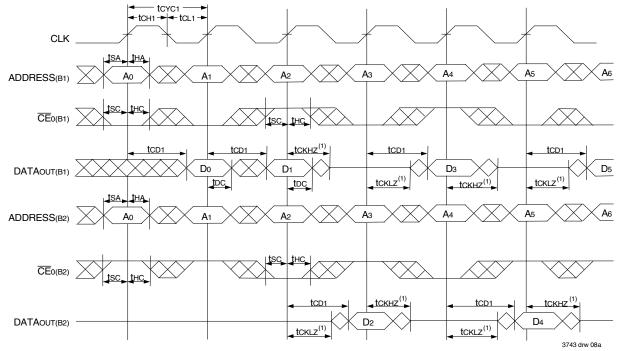
- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. $\overline{\text{OE}}$ is asynchronously controlled; all other inputs are synchronous to the rising clock edge.
- 3. $\overline{ADS} = VIL$, \overline{CNTEN} and $\overline{CNTRST} = VIH$.
- 4. The output is disabled (High-Impedance state) by $\overline{\text{CE}}_0 = \text{V}_{\text{IH}}$ or CE1 = V_{IL} following the next rising edge of the clock. Refer to Truth Table 1.
- 5. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 6. If $\overline{\sf UB}$ or $\overline{\sf LB}$ was HIGH, then the Upper Byte and/or Lower Byte of DATAouT for Qn + 2 would be disabled (High-Impedance state).
- 7. "x" denotes Left or Right port. The diagram is with respect to that port.



Timing Waveform of a Bank Select Pipelined Read (1,2)



Timing Waveform of a Bank Select Flow-Through Read⁽⁶⁾

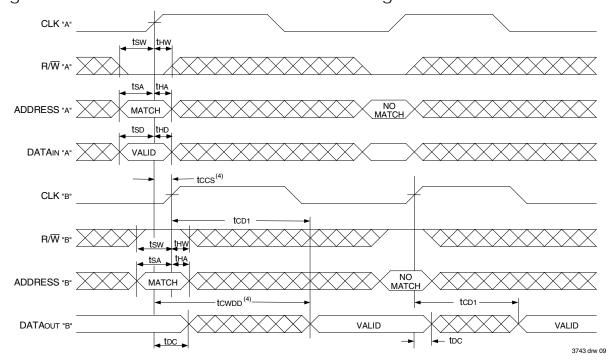


- 1. B1 Represents Bank #1; B2 Represents Bank #2. Each Bank consists of one IDT70V9279/69 for this waveform, and are setup for depth expansion in this example. ADDRESS(B1) = ADDRESS(B2) in this situation.
- 2. \overline{UB} , \overline{LB} , \overline{OE} , and \overline{ADS} = VIL; CE1(B1), CE1(B2), R/ \overline{W} , \overline{CNTEN} , and \overline{CNTRST} = VIH.
- 3. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 4. \overline{CE}_0 , \overline{UB} , \overline{LB} , and \overline{ADS} = VIL; CE1, \overline{CNTEN} , and \overline{CNTRST} = VIH.
- 5. \overline{OE} = V_{IL} for the Right Port, which is being read from. \overline{OE} = V_{IH} for the Left Port, which is being written to.
- 6. If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwpd.

 If tccs > maximum specified, then data from right port READ is not valid until tccs + tcp1. tcwpd does not apply in this case.



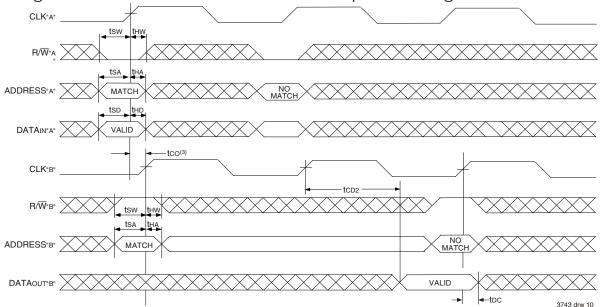
Timing Waveform with Port-to-Port Flow-Through Read^(1,2,3,5)



NOTES

- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. \overline{CE}_0 , \overline{UB} , \overline{LB} , and $\overline{ADS} = VIL$; \overline{CE}_1 , \overline{CNTEN} , and $\overline{CNTRST} = VIH$.
- 3. \overline{OE} = VIL for the Right Port, which is being read from. \overline{OE} = VIH for the Left Port, which is being written to.
- 4. If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwpb.
 If tccs > maximum specified, then data from right port READ is not valid until tccs + tcp1. tcwpb does not apply in this case.
- 5. All timing is the same for both left and right ports. Port "A" may be either left or right port. Port "B" is the opposite of Port "A".

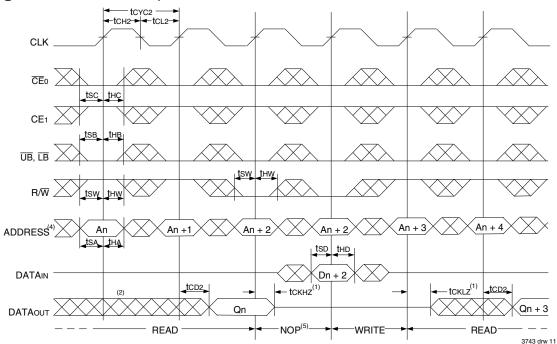
Timing Waveform of Left Port Write to Pipelined Right Port Read^(1,2,4)



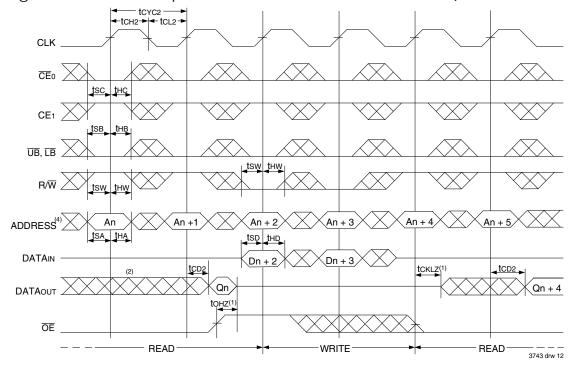
- 1. $\overline{CE_0}$, $\overline{BE_n}$, and $\overline{ADS} = VIL$; CE_1 , \overline{CNTEN} , and $\overline{REPEAT} = VIH$.
- 2. $\overline{OE} = V_{IL}$ for Port "B", which is being read from. $\overline{OE} = V_{IH}$ for Port "A", which is being written to.
- 3. If tco ≤ minimum specified, then data from Port "B" read is not valid until following Port "B" clock cycle (ie, time from write to valid read on opposite port will be tco + 2 tcyc2 + tco2). If tco > minimum, then data from Port "B" read is available on first Port "B" clock cycle (ie, time from write to valid read on opposite port will be tco + tcyc2 + tco2).
- 4. All timing is the same for Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite of Port "A"



Timing Waveform of Pipelined Read-to-Write-to-Read (**OE** = VIL)(3)



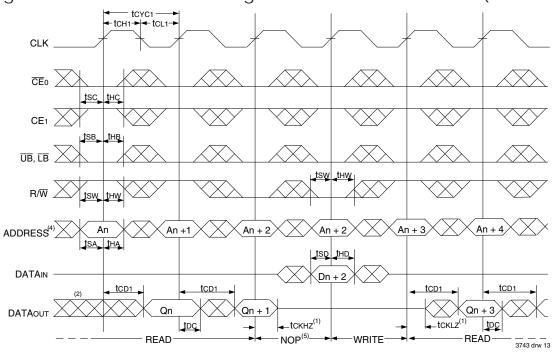
Timing Waveform of Pipelined Read-to-Write-to-Read (**OE** Controlled)(3)



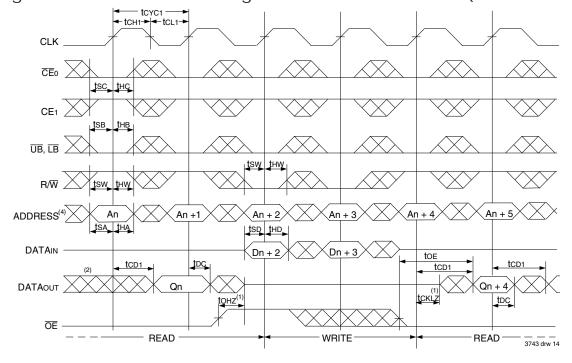
- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3. $\overline{\text{CE}}_0$, $\overline{\text{UB}}$, $\overline{\text{LB}}$, and $\overline{\text{ADS}} = \text{VIL}$; $\overline{\text{CE}}_1$, $\overline{\text{CNTEN}}$, and $\overline{\text{CNTRST}} = \text{VIH}$.
- 4. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be rewritten to guarantee data integrity.



Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** = VIL)(3)



Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** Controlled)⁽³⁾

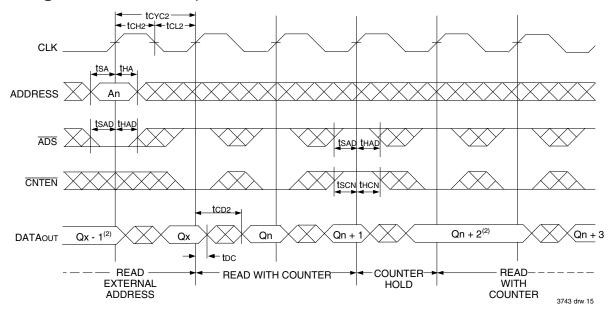


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3. \overline{CE}_0 , \overline{UB} , \overline{LB} , and \overline{ADS} = VIL; \overline{CE}_1 , \overline{CNTEN} , and \overline{CNTRST} = VIH.
- 4. Addresses do not have to be accessed sequentially since $\overline{ADS} = V_{IL}$ constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be rewritten to guarantee data integrity.

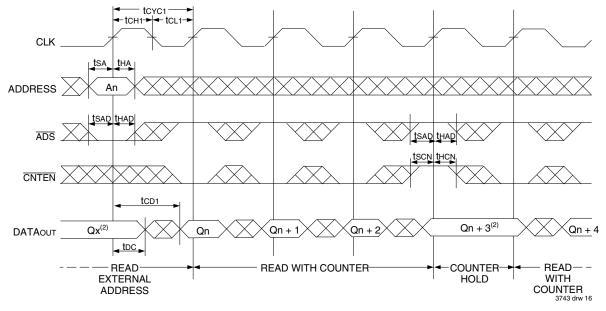


gri opeca ozi tott x to Daar t ott dynomonous otatio trans

Timing Waveform of Pipelined Read with Address Counter Advance⁽¹⁾



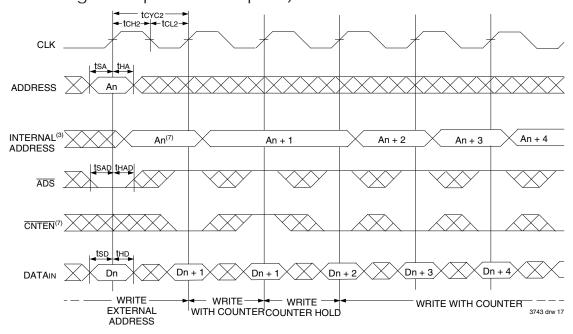
Timing Waveform of Flow-Through Read with Address Counter Advance⁽¹⁾



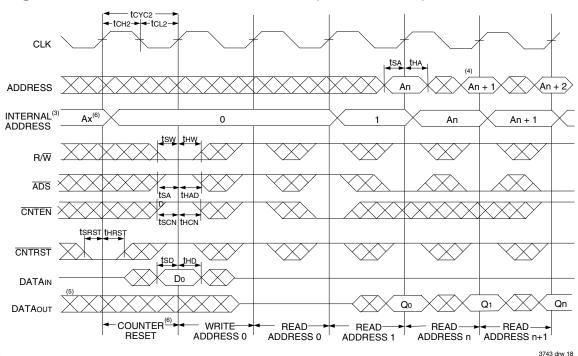
- 1. \overline{CE}_0 , \overline{OE} , \overline{UB} , and \overline{LB} = VIL; CE1, R/ \overline{W} , and \overline{CNTRST} = VIH.
- 2. If there is no address change via $\overline{ADS} = VIL$ (loading a new address) or $\overline{CNTEN} = VIL$ (advancing the address), i.e. $\overline{ADS} = VIH$ and $\overline{CNTEN} = VIH$, then the data output remains constant for subsequent clocks.



Timing Waveform of Write with Address Counter Advance (Flow-Through or Pipelined Outputs)⁽¹⁾



Timing Waveform of Counter Reset (Pipelined Outputs)(2)



- 1. $\overline{CE_0}$, \overline{UB} , \overline{LB} , and $R/\overline{W} = V_{IL}$; CE_1 and $\overline{CNTRST} = V_{IH}$.
- 2. \overline{CE}_0 , \overline{UB} , \overline{LB} = VIL; CE1 = VIH.
- 3. The "Internal Address" is equal to the "External Address" when ADS = V_{IL} and equals the counter output when ADS = V_{IL}
- 4. Addresses do not have to be accessed sequentially since $\overline{ADS} = V_{IL}$ constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 6. No dead cycle exists during counter reset. A READ or WRITE cycle may be coincidental with the counter reset cycle. ADDRo will be accessed. Extra cycles are shown here simply for clarification.
- 7. CNTEN = V_{IL} advances Internal Address from 'An' to 'An +1'. The transition shown indicates the time required for the counter to advance.
 The 'An +1'Address is written to during this cycle.

Functional Description

The IDT70V9279/69 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse is independent of the LOW to HIGH transition of the clock signal.

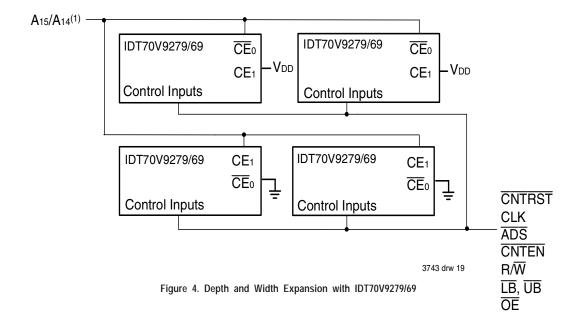
An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to staff the operation of the address counters for fast interleaved memory applications.

A HIGH on $\overline{\text{CE}}$ o or a LOW on CE1 for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT70V9279/69's for depth expansion configurations. When the Pipelined output mode is enabled, two cycles are required with $\overline{\text{CE}}$ 0 LOW and CE1 HIGH to reactivate the outputs.

Depth and Width Expansion

The IDT70V9279/69 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the various chip enables in order to expand two devices in depth.

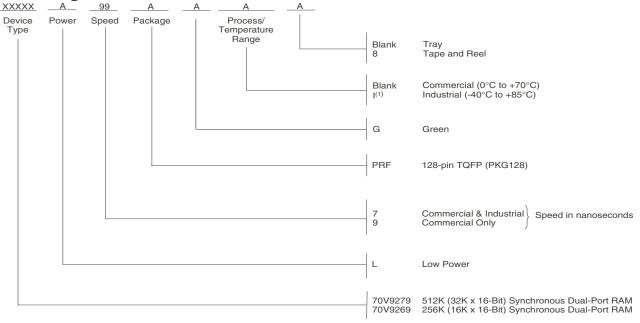
The IDT70V9279/69 can also be used in applications requiring expanded width, as indicated in Figure 4. Since the banks are allocated at the discretion of the user, the external controller can be set up to drive the input signals for the various devices as required to allow for 32-bit or wider applications.



NOTE:

1. A15 is for IDT70V9279. A14 is for IDT70V9269.





NOTES: 3743 drw 20

Contact your local sales office for industrial temp. range for other speeds, packages and powers.
 LEAD FINISH (SnPb) parts are Obsolete. Product Discontinuation Notice - PDN# SP-17-02
 Note that information regarding recently obsoleted parts are included in this datasheet for customer convenience.

Ordering Information for Flow-through Devices

Old Flow-through Part	New Combined Part
70V927S/L25	70V9279L7
70V927S/L30	70V9279L9

3743 tbl 12

IDT Clock Solution for IDT70V9279/69 Dual-Port

IDT Dual-Port Part Number	Dual-Port I/O Specitications		Clock Specifications				IDT	IDT
	Voltage	I/O	Input Capacitance	Input Duty Cycle Requirement	Maximum Frequency	Jitter Tolerance	PLL Clock Device	Non-PLL Clock Device
70V9279/69	3.3	LVTTL	9pF	40%	100	150ps	2305 2308 2309	49FCT3805 49FCT3805D/E 74FCT3807 74FCT3807D/E

3743 tbl 13

Orderable Part Information

or dor doro r dr t milormation				
Speed (ns)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade
7	70V9279L7PRFG	PKG128	TQFP	С
	70V9279L7PRFG8	PKG128	TQFP	С
	70V9279L7PRFGI	PKG128	TQFP	I
	70V9279L7PRFGI8	PKG128	TQFP	Ī

Speed (ns)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade
9	70V9269L9PRFG	PKG128	TQFP	С
	70V9269L9PRFG8	PKG128	TQFP	С



Industrial and Commercial Temperature Ranges

Datasheet Document History

01/12/99:		Initiated datasheet document history Converted to newformat Cosmetic and typographical corrections
		Added additional notes to pin configurations
	Page 14	Added Depth & Width Expansion section
06/15/99:	Page 4	Deleted note 6 for Table II
09/29/99:	Page 7	Corrected typo in heading
11/10/99:	r ago i	Replaced IDT logo
03/31/00:		Combined Pipelined 70V9279/69 family and Flow-through 70V927 family offerings into one data sheet
		Changed ±200mV in waveform notes to 0mV
		Added corresponding part chart with ordering information
01/017/01:	Page 4	Changed information in Truth Table II
	_	Increased storage temperature parameters
		Clarified TA parameter
	Page 5	DC Electrical parameters–changed wording from "open" to "disabled"
		Removed Preliminary status
02/25/04:		Consolidated multiple devices into one datasheet
		Changed naming conventions from Vcc to Vdd and from GND to Vss
	Page 2	Added date revision for pin configuration
	Page 3	Added footnotes for \overline{UB} , \overline{LB} , $\overline{CE}0$ and CE1 buffer conditions when \overline{FT} or PIPE
	Page 4	Added junction temperature to Absolute Maximum Ratings Table
	D - E	Added Ambient Temperature footnote
	Page 5	Added I-temp numbers for 9ns speed to DC Electrical Characteristics Table
	D7	Added 6ns speed DC power numbers to the DC Electrical Characteristics Table
	Page 7	Added I-temp for 9ns speed to AC Electrical Characteristics Table
	Dago 10	Added 6ns speed AC timing numbers to the AC Electrical Characteristics Table
	Page 18	Added 6ns speed grade and 9ns I-temp to ordering information Added IDT Clock Solution Table
	Page 1 & 19	Updated IDT logo, replaced IDTτω logo with IDT® logo
05/04/04:	Page 1 & 18	Added 7ns speed grade to ordering information
03/04/04.	Page 5	Added 7ns speed DC power numbers to the DC Electrical Characteristics Table
	Page 8	Added 7ns speed AC timing numbers to the AC Electrical Characteristics Table
10/11/04:	Page 4	Updated Capacitance table
	Page 5	Added 7ns I-temp and removed 9ns I-temp DC power numbers from the DC Electrical Characteristics table
	Page 8	Added 7ns I-temp and removed 9ns I-temp from the AC Electrical Characteristics table
	Page 12	Added Timing Waveform of Left Port Write to Pipelined Right Port Read
	Page 18	Added 7ns I-temp and removed 9ns I-temp from ordering information
01/19/06:	Page 1	Added green availability to features
	Page 18	Added green indicator to ordering information
10/23/08:	Page18	Removed "IDT" from orderable part number
06/25/18:		Added Tape & Reel to Ordering Information
		Product Discontinuation Notice - PDN# SP-17-02
	_	Last time buy expires June 15, 2018
08/06/19:	Page 1 & 18	Deleted obsolete Commercial speed grades 6/12/15ns
	Page 2	Updated package code PK-128 to PKG128
	Page 18	Added Orderable Part Information table

IMPORTANT NOTICE AND DISCLAIMER

RENESAS ELECTRONICS CORPORATION AND ITS SUBSIDIARIES ("RENESAS") PROVIDES TECHNICAL SPECIFICATIONS AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS OR IMPLIED, INCLUDING, WITHOUT LIMITATION, ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for developers skilled in the art designing with Renesas products. You are solely responsible for (1) selecting the appropriate products for your application, (2) designing, validating, and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. Renesas grants you permission to use these resources only for development of an application that uses Renesas products. Other reproduction or use of these resources is strictly prohibited. No license is granted to any other Renesas intellectual property or to any third party intellectual property. Renesas disclaims responsibility for, and you will fully indemnify Renesas and its representatives against, any claims, damages, costs, losses, or liabilities arising out of your use of these resources. Renesas' products are provided only subject to Renesas' Terms and Conditions of Sale or other applicable terms agreed to in writing. No use of any Renesas resources expands or otherwise alters any applicable warranties or warranty disclaimers for these products.

(Rev.1.0 Mar 2020)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

Contact Information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:

www.renesas.com/contact/

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for SRAM category:

Click to view products by Renesas manufacturer:

Other Similar products are found below:

CY6116A-35DMB CY7C1049GN-10VXI GS8161Z36DD-200I GS88237CB-200I RMLV0408EGSB-4S2#AA0 IDT70V5388S166BG
IS64WV3216BLL-15CTLA3 IS66WVE4M16ECLL-70BLI PCF8570P K6F2008V2E-LF70000 K6T4008C1B-GB70 CY7C1353S-100AXC
AS6C8016-55BIN AS7C164A-15PCN 515712X IDT71V67603S133BG IS62WV51216EBLL-45BLI IS63WV1288DBLL-10HLI
IS66WVE2M16ECLL-70BLI IS66WVE4M16EALL-70BLI IS61WV102416DBLL-10TLI CY7C1381KV33-100AXC CY7C1381KVE33133AXI 8602501XA 5962-3829425MUA 5962-3829430MUA 5962-8866201YA 5962-8866204TA 5962-9062007MXA 59629161705MXA GS882Z18CD-150I 8413202RA 5962-8866208YA 5962-8866203YA IS61WV102416DBLL-10BLI IS66WVC2M16ECLL7010BLI CY7C1380KV33-250AXC AS6C8016-55BINTR GS81284Z18B-250I AS7C34096B-10TIN GS84018CB-200I
IS62WV25616EALL-55TLI IS61WV204816BLL-10TLI GS8128418B-167IV CY7C1460KV25-200BZXI CY7C1315KV18-333BZXC
CY62157G30-45ZSXI 71V016SA12YG RMLV0416EGBG-4S2#AC0 CY62126EV18LL-70BVXI